



Thin-Wire Wedge-Wedge Bonder 5830

Bond System

Wire types	Aluminium and gold wire 17,5-75µm on 2" spool
Bondhead	Wedge-Wedge for thin wire Standard tool of 1" length, 45° wire feed Motorized wire spool (optional)
Ultrasonic System	F&S Generator 100 kHz (optional 65, 140kHz)

Bonder Base

Axes

- Working area X/Y-axis 200 x 150 mm;
- Programmable step resolution 1µm
- Programmable Z axis with 100 mm stroke;

Hardware

- Dual-Core PC with Windows 7 OS, Ethernet,
- USB 2.0/3.0, Colour Display 22"
- GigE-CCD-Colour Camera, 5 Mpixel
- Fully networkable in TCP/IP servers

Software

- From single bonds up to complex programmes,
- Loop shapes can be saved in libraries
- Optional pattern recognition

Control

- high-performance embedded ARM-System with Real-time operating system for precision
- 1 wire / second

Placement accuracy: +/- 5µm @ 3 sigma, incl. Tool / no wire on F & S Bondtec standard substrate

Repeatability: +/- 3 µm @ 3 sigma, incl. Tool / without wire on F & S Bondtec standard substrate

Loop height accuracy: +/- 5µm @ 3 sigma, for thin wire 5830 with 25µm aluminum wire on F & S Bondtec standard substrate

The 58xx series:

The thin-wire wedge-wedge version of the automatic wire bonders in our Series 58xx featuring exchangeable bond heads.

A fully automatic mode makes it ideally suited for medium-scale production. Parts to be bonded are fed manually by the operator, but the bonds are produced completely without operator influence. Thanks to the built-in pattern recognition.

Single bonds can be made within seconds, making the machine perfect for R&D, Pilot manufacturing and middle volume production.

BONDING THE STARS



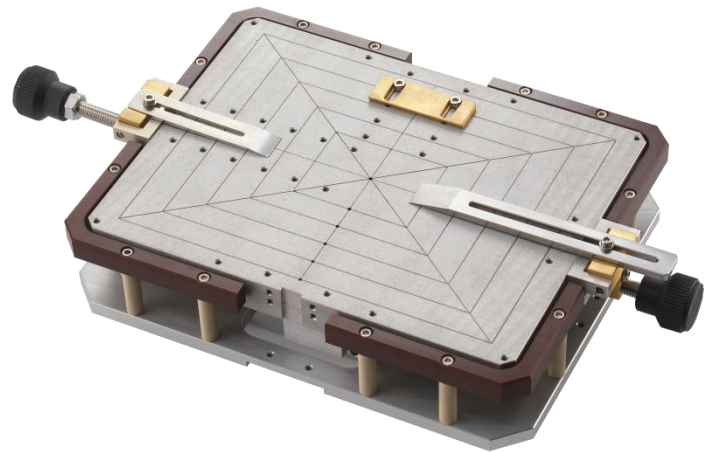
Dimensions W x D x H 92x71x65 cm, weight approx. 80 kg

Connections 100-240 VAC, 1 Phase, 50/60 Hz, max 230 VA
Ø 6 mm standard vacuum tubing

Heater controller Integrated in the machine 0-250°C

Workholder

Standard-Workholder
for parts up to 8x6"
with Vacuum and mechanical clamping



Optional:



6x6" workholder with Vacuum and mechanical clamping



TO Workholder with mechanical clamping



4x4" workholder with . rubberized surface and mechanical clamping

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